

Cypress CYV15G0403DXB HOTLink II Video Demonstration Board, Rev 1

April 26, 2004

Board size: 6" x 8"

Thickness: 84 ±5 mil

Material: FR-408

Solder mask: LPI, both sides

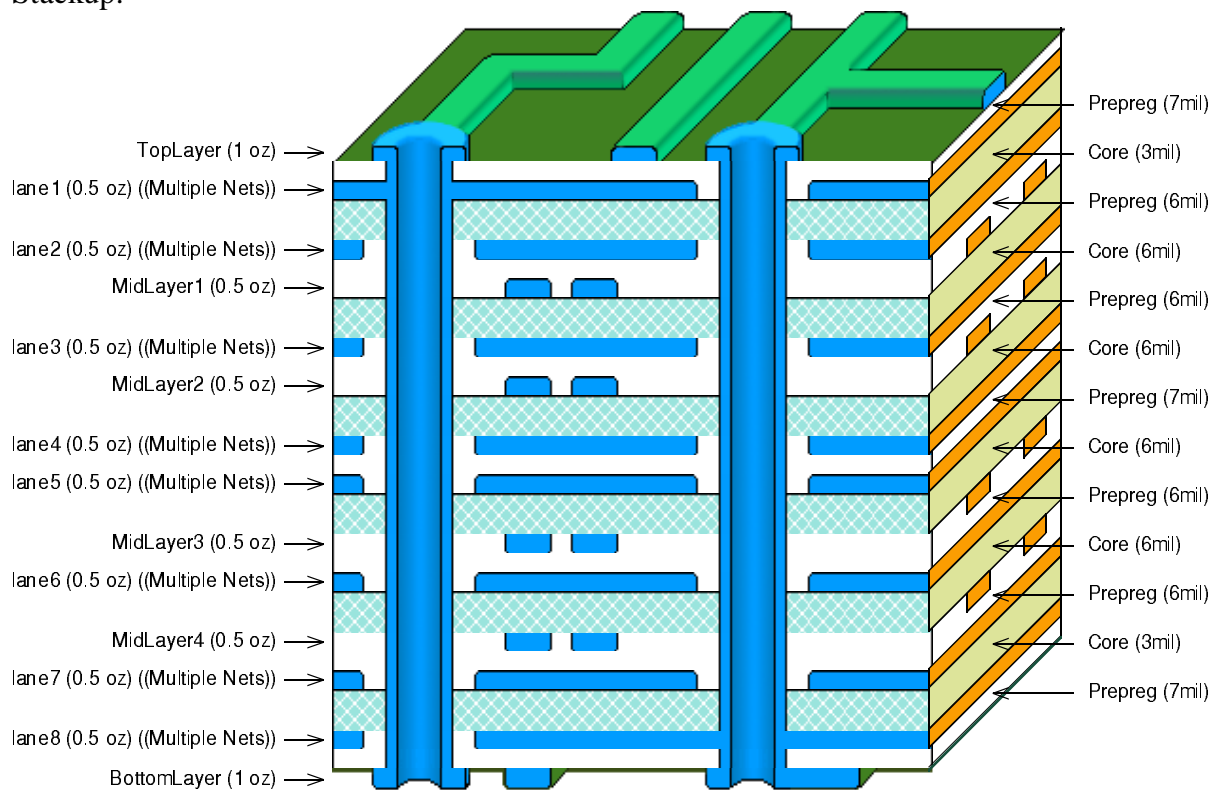
Silkscreen: white, both sides

Hot air solder level (SMOBC): yes

Bare board test: yes

Commercial quality

Stackup:



- we don't care which dielectric layers are core and which are prepreg
- all copper weights are finished weights
- 5.067mil traces on MidLayer1 and MidLayer4 should have 50 ohm characteristic impedance
- 12.343mil traces on TopLayer should have 50 ohm characteristic impedance
- 5.564mil traces on TopLayer should have 75 ohm characteristic impedance
- pair of 13.59mil traces on TopLayer should have 90 ohm differential impedance

Contents of molson20040426.zip:

MolsonPCB.DRL	Excellon drill file	binary
MolsonPCB.DRR	NC drill report	text
MolsonPCB.G1	MidLayer1	RS274-X
MolsonPCB.G2	MidLayer2	RS274-X
MolsonPCB.G3	MidLayer3	RS274-X
MolsonPCB.G4	MidLayer4	RS274-X
MolsonPCB.GBL	BottomLayer	RS274-X
MolsonPCB.GBO	BottomOverlay	RS274-X
MolsonPCB.GBP	BottomPaste	RS274-X
MolsonPCB.GBS	BottomSolder	RS274-X
MolsonPCB.GP1	InternalPlane1	RS274-X
MolsonPCB.GP2	InternalPlane2	RS274-X
MolsonPCB.GP3	InternalPlane3	RS274-X
MolsonPCB.GP4	InternalPlane4	RS274-X
MolsonPCB.GP5	InternalPlane5	RS274-X
MolsonPCB.GP6	InternalPlane6	RS274-X
MolsonPCB.GP7	InternalPlane7	RS274-X
MolsonPCB.GP8	InternalPlane8	RS274-X
MolsonPCB.GTL	TopLayer	RS274-X
MolsonPCB.GTO	TopOverlay	RS274-X
MolsonPCB.GTP	TopPaste	RS274-X
MolsonPCB.GTS	TopSolder	RS274-X
MolsonPCB.TXT	Excellon drill file	text
molsonrev1assy.pdf	Assembly drawing	PDF
Pick Place for MolsonPCB.csv	Pick and place file	CSV
Pick Place for MolsonPCB.txt	Pick and place file	text

There are four unplated 156mil tooling holes.